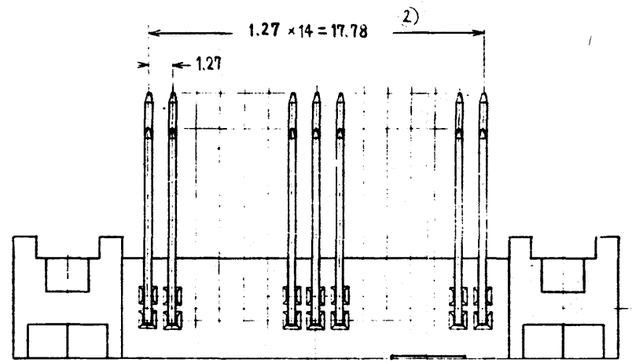
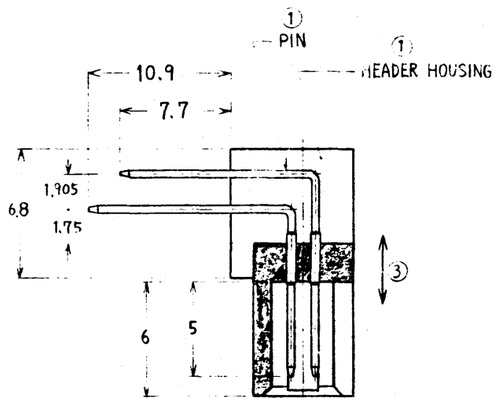
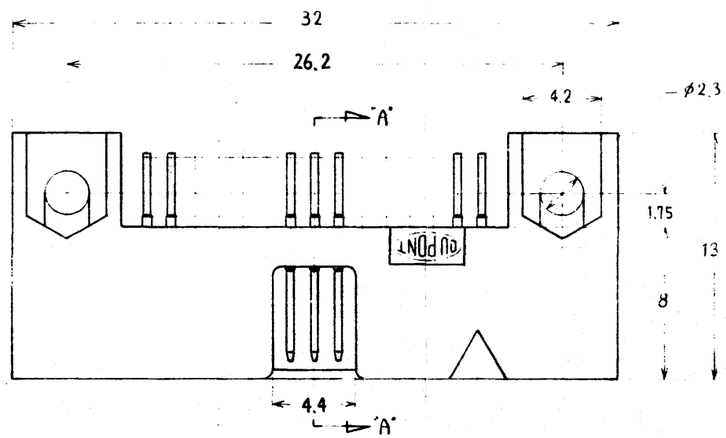
PRODUCT NO
71332 -001

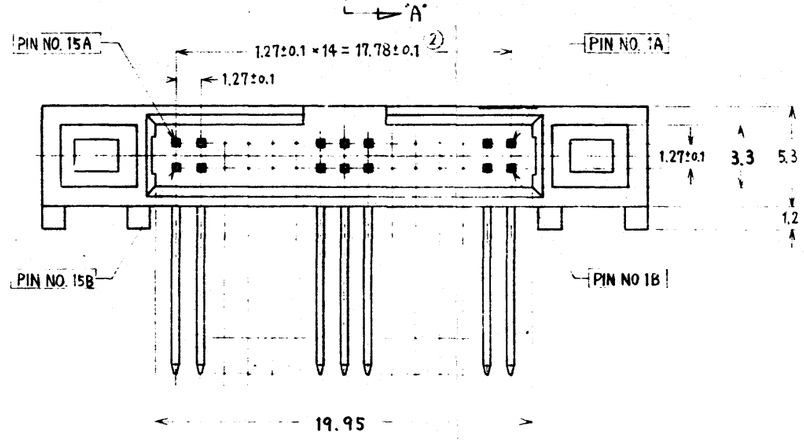
REVISIONS			
REV	DESCRIPTION	BY	DATE
A	RELEASED	N.H	10/22/'86
B	REVISED	N.H	3/4/'87
C	REVISED	N.H	4/6/'87
D	REVISED	N.H	12/24/87

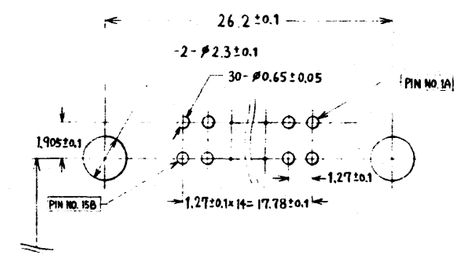




SECT. "A" - "A"







17.5 MAX.
(FROM A EDGE OF PCB.)

RECOMMENDED MOUNTING DIMENSION (TOP VIEW)

NOTES
① MATERIAL AND FINISH
PIN
MATERIAL – PHOS. BRO.
FINISH – ALL OVER Ni UNDERPLATING 0.5 μm THK. MIN.
CONTACT AREA : Au PLATING 0.1 μm THK. MIN. OVER Pd-Ni PLATING.
SOLDER TAIL : SnPb (9/1) PLATING 3.8 μm THK. MIN.
HEADER HOUSING
MATERIAL – 66 NYLON GLASS 25% FILLED, UL 94 V-0, COLOR : BLACK

② TO BE NONCUMULATIVE TOLERANCE.

③ PIN RETENTION FORCE AGAINST THIS DIRECTION 0.5 kg/PIN MIN.

注
① 材質および仕上
ピン
材質 – リン青銅
仕上 – 全面下地 Niメッキ 厚さ0.5 μm 以上.
接触部 : Pd-Niメッキ上 Auメッキ厚さ0.1 μm 以上
半田付部 : 半田メッキ(9/1) 厚さ3.8 μm 以上.
ヘッダー ハウジング
材質 – ナイロン'6 ガラス25%入り, UL 94 V-0, 色 : 黒色.

② 公差は累積しない.

③ この方向に対するピンの保持力 0.5 kg/ピン以上.

SHEET INDEX	ISSUE	
	SH NO	1

CUSTOMER COPY

CODE IDENT 22526

DU PONT CONNECTOR SYSTEMS

LEVELS	DO NOT SCALE DRAWING	TOLERANCE UNLESS OTHERWISE NOTED MM/~~INCH~~ ±0.3	MATL SEE NOTE ① 注①参照	DR	DATE 10/22/'86
	THIRD ANGLE PROJECTION	LINEAR: 0.00±0.25/.00±.01; 0.000±0.13/.000±.005; 0.0000±0.051/.0000±.0020	FINISH SEE NOTE ① 注①参照	CHK H. Lee	10/23/'86
TABULATION SHEETS REQUIRED YES / NO	MM / ~~INCH~~	ANGLES ±2°0'		ENGR	10/22/'86
				APPD	11/13/86

TITLE
M-STYLE MEMORY CASSETTE R/A HEADER ASS'Y

SCALE	SIZE	DWG NO	
5-1	C	71332	SHEET 1/1